KYOCERA

KYOCERA Chemical Corporation
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Molding Compounds for Surface Mount Devices

Standard (Br/Sb) type

We have several grades of compounds w/ good balance between cost and performance to meet wide requirements of customers.

Strong Points

a) Good Adhesion Strength even Under High Temperature Reflow Soldering Process.
b) Achieve Good Reflow Resistance (JEDEC Level 2) with Good Moldability.
c) JEDEC Level 1 in Case Smaller Package is possible.
d) Line Up for Several Lead Frame Types. (Cu,42Alloy,Pd/Au plated)

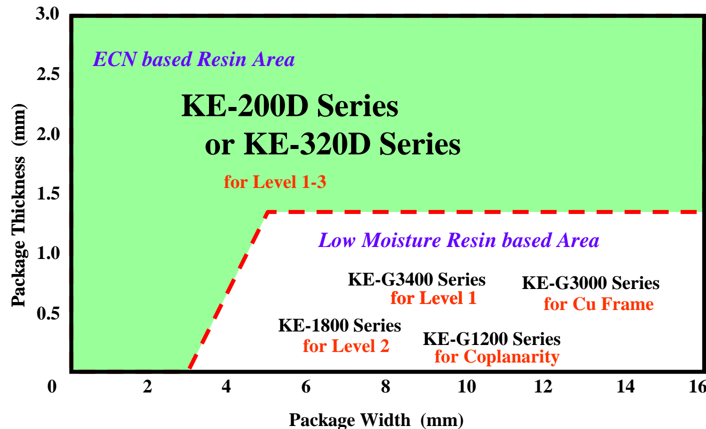
Application

・SOP ・Larger QFP ・Smaller QFP ・DIP ・TO-PKG ・DPAK ・SOT

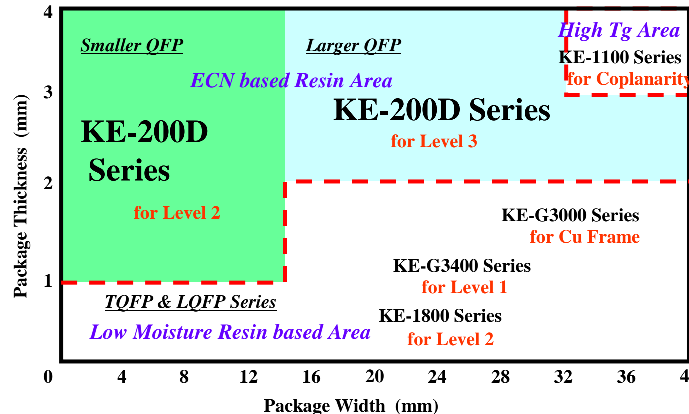
General Properties

Item		Units	KE-320D	KE-200DH	KE-200DC-1
Spiral flow		cm	95	85	110
Gel time		s	25	23	27
Specific gravity		-	1.9	2.0	2.0
C.T.E	α1	$x10^{-5}/^oC$	1.3	1.1	1.1
	α2		5.3	4.5	4.5
Glass transition temp.		^oC	145	130	130
Flexural strength		MPa	150	145	155
Flexural modulus		GPa	16.0	18.0	21.0

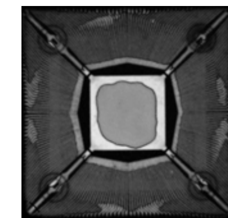
For SOP



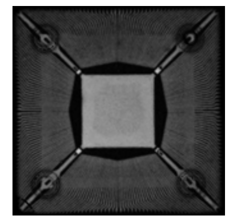
For QFP



Delamination Resistance
(Interface between Die pad and Resin by SAT)



Conventional Epoxy Molding Compound



KE-200DC-1

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